IPC ASSOCIATION CONNECTELECTRONICS INDUSTRI	Material Compo © Copyright 2005. IP international and Pan-	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfg Information			
upplier Infor	mation														
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
onsemi											2024-05	2024-05-12			
Contact Name		Title - Contact			1	Phone - Contact*				Email -	Email - Contact*				
Product-Env-Ste	wards		Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
uthorized Repre	esentative*	Title - Representative]	Phone - Representative*				Email -	Email - Representative*				
Product-Env-Ste	wards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
Reque	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Dat	e Versi	on	Manufacturing Site		Weight*	UOM	Unit Type	
		FAN604	FAN604HMX QR Flyback CCR pin (pin to 20V		2024-05-12			TAD		77.8214	mg	Each	
Ianufacturin	g Proccess Informat														
Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Temp		/ Temperatu			ture Numb	er of Reflow Cyc	eles		
Matte Tin (Sn) - annealed CU			CU Alloy 3				260 C 30		seco	nds 3					
omments															
TTENTION: M	SL 3 Rated item requires	Bake and D	ry Pack (afte	r electrical test)											
or more informa	ation regarding material o	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct one bents it is form. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.43	mg	Supplier	Silicon (Si)	7440-21-3		1.43	mg
Die Attach	0.0631	mg		Epoxy resin	proprietary data		0.0063	mg
			Supplier	Silver (Ag)	7440-22-4		0.0505	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.0063	mg
Lead Frame	25.2775	mg	Supplier	Silver (Ag)	7440-22-4		0.0202	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0506	mg
			Supplier	Iron (Fe)	7439-89-6		0.632	mg
			Supplier	Copper (Cu)	7440-50-8		24.5494	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0253	mg
Mold Compound-Black	48.6018	mg		Epoxy resin	proprietary data		3.4021	mg
			Supplier	Phenolic Resin	Proprietary Data		1.4581	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.8602	mg
			Supplier	Carbon Black (C)	1333-86-4		0.243	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.6384	mg
Plating	2.37	mg	Supplier	Tin (Sn)	7440-31-5		2.37	mg
Wire Bond - Au	0.079	mg	Supplier	Gold (Au)	7440-57-5		0.079	mg